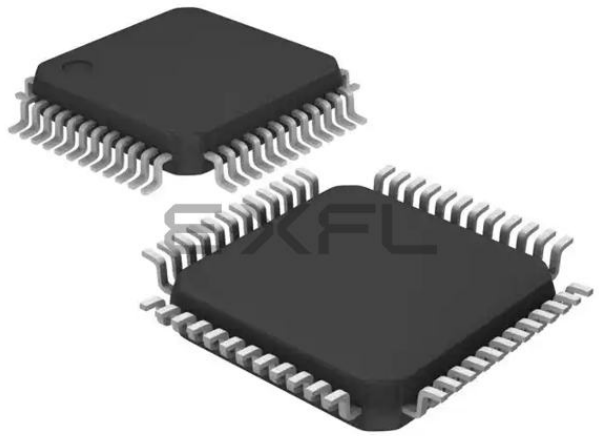

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	S12Z
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, I²C, IrDA, LINbus, SCI, SPI, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	5.5V ~ 18V
Data Converters	A/D 10x10b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s912zvla96f0mlf

The MC9S12ZVL family of microcontrollers is targeted at use in safety relevant systems and has been developed using an ISO26262 compliant development system under the NXP Safe Assure program.

For more details of how to use the device in safety relevant systems refer to the MC9S12ZVL Safety Manual at :

http://nxp.com/S12ZVL

To provide the most up-to-date information, the revision of our documents on the World Wide Web will be the most current. Your printed copy may be an earlier revision. To verify you have the latest information available, refer to:

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A full list of family members and options is included in the device overview section.

This document contains information for all constituent modules, with the exception of the S12Z CPU. For S12ZCPU information please refer to the CPU S12Z Reference Manual.

NOTE

This reference manual documents the entire S12ZVL-Family. It contains a superset of features within the family. Some module versions differ from one part to another within the family. Section 1.2.1 MC9S12ZVL-Family Member Comparison provides support to access the correct information for a particular part within the family.

PP[5,3,1] connect the loads to the digital ground VSSX.

Similar protection mechanisms as for EVDD1 apply for PP[5,3,1] accordingly in an inverse way.

2.5.5 Open Input Detection on HVI

The connection of an external pull device on a high-voltage input can be validated by using the built-in pull functionality of the HVI. Depending on the application type an external pull-down circuit can be detected with the internal pull-up device whereas an external pull-up circuit can be detected with the internal pull-down device which is part of the input voltage divider.

Note that the following procedures make use of a function that overrides the automatic disable mechanism of the digital input buffer when using the HVI in analog mode. Make sure to switch off the override function when using the HVI in analog mode after the check has been completed.

External pull-down device (Figure 2-33):

1. Enable analog function on HVI in non-direct mode (PTAL[PTAENL]=1, PTAL[PTADIRL]=0)
2. Select internal pull-up device on HVI (PTAL[PTPSL]=1)
3. Enable function to force input buffer active on HVI in analog mode (PTAL[PTTEL]=1)
4. Verify PTIL=0 for a connected external pull-down device; read PTIL=1 for an open input

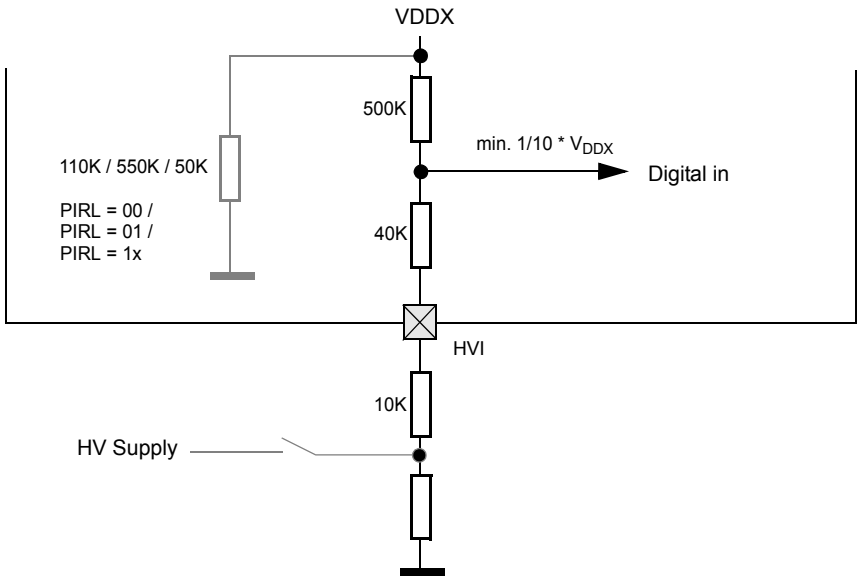

Figure 2-33. Digital Input Read with Pull-up Enabled

External pull-up device (Figure 2-34):

1. Enable analog function on HVI in non-direct mode (PTAL[PTAENL]=1, PTAL[PTADIRL]=0)
2. Select internal pulldown device on HVI (PTAL[PTPSL]=0)
3. Enable function to force input buffer active on HVI in analog mode (PTAL[PTTEL]=1)

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0070	MODE	R	MODC	0	0	0	0	0	0	0
		W								
0x0071-0x007F	Reserved	R	0	0	0	0	0	0	0	0
		W								
0x0080	MMCECH	R	ITR[3:0]				TGT[3:0]			
		W								
0x0081	MMCECL	R	ACC[3:0]				ERR[3:0]			
		W								
0x0082	MMCCCRH	R	CPUU	0	0	0	0	0	0	0
		W								
0x0083	MMCCCRL	R	0	CPUX	0	CPUI	0	0	0	0
		W								
0x0084	Reserved	R	0	0	0	0	0	0	0	0
		W								
0x0085	MMCPCH	R	CPUPC[23:16]							
		W								
0x0086	MMCPCM	R	CPUPC[15:8]							
		W								
0x0087	MMCPCL	R	CPUPC[7:0]							
		W								
0x0088-0x00FF	Reserved	R	0	0	0	0	0	0	0	0
		W								

= Unimplemented or Reserved

Figure 4-2. S12ZDBG Register Summary

4.3.2 Register Descriptions

This section consists of the S12ZDBG control and status register descriptions in address order.

  - Double bit error detection per 2 byte data word
- Memory initialization function
- Byte wide system memory write access
- Automatic single bit ECC error correction for read and write accesses
- Debug logic to read and write raw use data and ECC values

8.2 Memory Map and Register Definition

This section provides a detailed description of all memory and registers for the SRAM_ECC module.

8.2.1 Register Summary

Figure 8-1 shows the summary of all implemented registers inside the SRAM_ECC module.

Table 8-10. SRAM_ECC Interrupt Sources

Module Interrupt Sources	Local Enable
Single bit ECC error	ECCIE[SBEEIE]

8.3.6 ECC Algorithm

The table below shows the equation for each ECC bit based on the 16 bit data word.

Table 8-11. ECC Calculation

ECC bit	Use data
ECC[0]	~ (^ (data[15:0] & 0x443F))
ECC[1]	~ (^ (data[15:0] & 0x13C7))
ECC[2]	~ (^ (data[15:0] & 0xE1D1))
ECC[3]	~ (^ (data[15:0] & 0xEE60))
ECC[4]	~ (^ (data[15:0] & 0x3E8A))
ECC[5]	~ (^ (data[15:0] & 0x993C))

8.3.7 ECC Debug Behavior

For debug purposes, it is possible to read and write the uncorrected use data and the raw ECC value directly from the memory. For these debug accesses a register interface is available. The debug access is performed with the lowest priority; other memory accesses must be done before the debug access starts. If a debug access is requested during an ongoing memory initialization process, then the debug access is performed if the memory initialization process is done.

If the ECCDRR bit is set, then the automatic single bit ECC error repair function for all read accesses is disabled. In this case a read access from a system memory location with single bit ECC error will produce correct data and the single bit ECC error is flagged by the SBEEIF, but the data inside the system memory are unchanged.

By writing wrong ECC values into the system memory the debug access can be used to force single and double bit ECC errors to check the software error handling.

It is not possible to set the ECCDW or ECCDR bit if the previous debug access is ongoing (ECCDW or ECCDR bit active). This ensures that the ECCDD and ECCDE registers contains consistent data. The software should read out the status of the ECCDW and ECCDR register bit before a new debug access is requested.

8.3.7.1 ECC Debug Memory Write Access

Writing one to the ECCDW bit performs a debug write access to the memory address defined by register DPTR. During this access, the raw data DDATA and the ECC value DECC are written directly into the system memory. If the debug write access is done, the ECCDW register bit is cleared. The debug write

9.1.1 Features

The Pierce Oscillator (XOSCLCP) contains circuitry to dynamically control current gain in the output amplitude. This ensures a signal with low harmonic distortion, low power and good noise immunity.

- Supports crystals or resonators from 4MHz to 20MHz.
- High noise immunity due to input hysteresis and spike filtering.
- Low RF emissions with peak-to-peak swing limited dynamically
- Transconductance (gm) sized for optimum start-up margin for typical crystals
- Dynamic gain control eliminates the need for external current limiting resistor
- Integrated resistor eliminates the need for external bias resistor
- Low power consumption: Operates from internal 1.8V (nominal) supply, Amplitude control limits power
- Optional oscillator clock monitor reset
- Optional full swing mode for higher immunity against noise injection on the cost of higher power consumption and increased emission

The Voltage Regulator (VREGAUTO) has the following features:

- Input voltage range from 6 to 18V (nominal operating range)
- Low-voltage detect (LVD) with low-voltage interrupt (LVI)
- Power-on reset (POR)
- Low-voltage reset (LVR)
- On Chip Temperature Sensor and Bandgap Voltage measurement via internal ADC channel.
- Voltage Regulator providing Full Performance Mode (FPM) and Reduced Performance Mode (RPM)
- External ballast device support to reduce internal power dissipation
- Capable of supplying both the MCU internally plus external components
- Over-temperature interrupt

The Phase Locked Loop (PLL) has the following features:

- Highly accurate and phase locked frequency multiplier
- Configurable internal filter for best stability and lock time
- Frequency modulation for defined jitter and reduced emission
- Automatic frequency lock detector
- Interrupt request on entry or exit from locked condition
- PLL clock monitor reset
- Reference clock either external (crystal) or internal square wave (1MHz IRC1M) based.
- PLL stability is sufficient for LIN communication in slave mode, even if using IRC1M as reference clock

The Internal Reference Clock (IRC1M) has the following features:

– Enable the external oscillator (OSCE bit).
– Wait for oscillator to start up (UPOSC=1).
– Select the Oscillator Clock (OSCCLK) as source of the Bus Clock (PLLSEL=0).

— The PLLCLK is on and used to qualify the external oscillator clock.

9.1.2.2 Wait Mode

For S12CPMU_UHV Wait Mode is the same as Run Mode.

9.1.2.3 Stop Mode

Stop mode can be entered by executing the CPU STOP instruction. See device level specification for more details.

The voltage regulator is in Reduced Performance Mode (RPM).

NOTE

The voltage regulator output voltage may degrade to a lower value than in Full Performance Mode (FPM), additionally the current sourcing capability is substantially reduced (see also Appendix for VREG electrical parameters). Only clock source ACLK is available and the Power On Reset (POR) circuitry is functional. The Low Voltage Interrupt (LVI) and Low Voltage Reset (LVR) are disabled.

The API is available.

The Phase Locked Loop (PLL) is off.

The Internal Reference Clock (IRC1M) is off.

Core Clock and Bus Clock are stopped.

Depending on the setting of the PSTP and the OSCE bit, Stop Mode can be differentiated between Full Stop Mode (PSTP = 0 or OSCE=0) and Pseudo Stop Mode (PSTP = 1 and OSCE=1). In addition, the behavior of the COP in each mode will change based on the clocking method selected by COPOSCSEL[1:0].

- **Full Stop Mode (PSTP = 0 or OSCE=0)**
  External oscillator (XOSCLCP) is disabled.
  — If COPOSCSEL1=0:
  The COP and RTI counters halt during Full Stop Mode.
  After wake-up from Full Stop Mode the Core Clock and Bus Clock are running on PLLCLK (PLLSEL=1). COP and RTI are running on IRCCLK (COPOSCSEL0=0, RTIOSCSEL=0).
  — If COPOSCSEL1=1:
  The clock for the COP is derived from ACLK (trimmable internal RC-Oscillator clock). During Full Stop Mode the ACLK for the COP can be stopped (COP static) or running (COP active) depending on the setting of bit CSAD. When bit CSAD is set the ACLK clock source for the

Table 10-22. Conversion Interrupt Flag Select

CON_IF[15:1]	INTFLG_SEL[3]	INTFLG_SEL[2]	INTFLG_SEL[1]	INTFLG_SEL[0]	Comment
0x0000	0	0	0	0	No flag set
0x0001	0	0	0	1	Only one flag can be set (one hot coding)
0x0002	0	0	1	0	
0x0004	0	0	1	1	
0x0008	0	1	0	0	
0x0010	0	1	0	1	
....	...	...	...	...	
0x0800	1	1	0	0	
0x1000	1	1	0	1	
0x2000	1	1	1	0	
0x4000	1	1	1	1	

10.6.3.3 ADC List Usage and Conversion/Conversion Sequence Flow Description

It is the user's responsibility to make sure that the different lists do not overlap or exceed the system RAM area respectively the CSL does not exceed the NVM area if located in the NVM. The error flag IA_EIF will be set for accesses done outside the system RAM area and will cause an error interrupt if enabled for lists that are located in the system RAM.

Generic flow for ADC register load at conversion sequence start/restart:

- It is mandatory that the ADC is idle (no ongoing conversion or conversion sequence).
- It is mandatory to have at least one CSL with valid entries. See also Section 10.9.7.2, "Restart CSL execution with currently active CSL or Section 10.9.7.3, "Restart CSL execution with new/other CSL (alternative CSL becomes active CSL) — CSL swapping for more details on possible scenarios.
- A Restart Event occurs, which causes the index registers to be cleared (register ADCCIDX and ADCRIDX are cleared) and to point to the top of the corresponding lists (top of active RVL and CSL).
- Load conversion command to background conversion command register 1.
- The control bit(s) RSTA (and LDOK if set) are cleared.
- Wait for Trigger Event to start conversion.

Generic flow for ADC register load during conversion:

- The index registers ADCCIDX is incremented.
- The inactive background command register is loaded with a new conversion command.

Generic flow for ADC result storage at end of conversion:

- Index register ADCRIDX is incremented and the conversion result is stored in system RAM. As soon as the result is successfully stored, any conversion interrupt flags are set accordingly.
- At the conversion boundary the other background command register becomes active and visible in the ADC register map.
- If the last executed conversion command was of type "End Of Sequence", the ADC waits for the Trigger Event.
- If the last executed conversion command was of type "End Of List" and the ADC is configured in "Restart Mode", the ADC sets all related flags and stays idle awaiting a Restart Event to continue.
- If the last executed conversion command was of type "End Of List" and the ADC is configured in "Trigger Mode", the ADC sets all related flags and automatically returns to top of current CSL and is awaiting a Trigger Event to continue.
- If the last executed conversion command was of type "Normal Conversion" the ADC continues command execution in the order of the current CSL (continues conversion).

10.9.9 Triggered Conversion — Single CSL

Applications that require the conversion of one or more groups of different channels in a periodic and timed manner can make use of a configuration in “Trigger Mode” with a single CSL containing a list of sequences. This means the CSL consists of several sequences each separated by an “End of Sequence” command. The last command of the CSL uses the “End Of List” command with wrap to top of CSL and waiting for a Trigger (CMD_SEL[1:0] =2’b11). Hence after the initial Restart Event each sequence can be launched via a Trigger Event and repetition of the CSL can be launched via a Trigger after execution of the “End Of List” command.

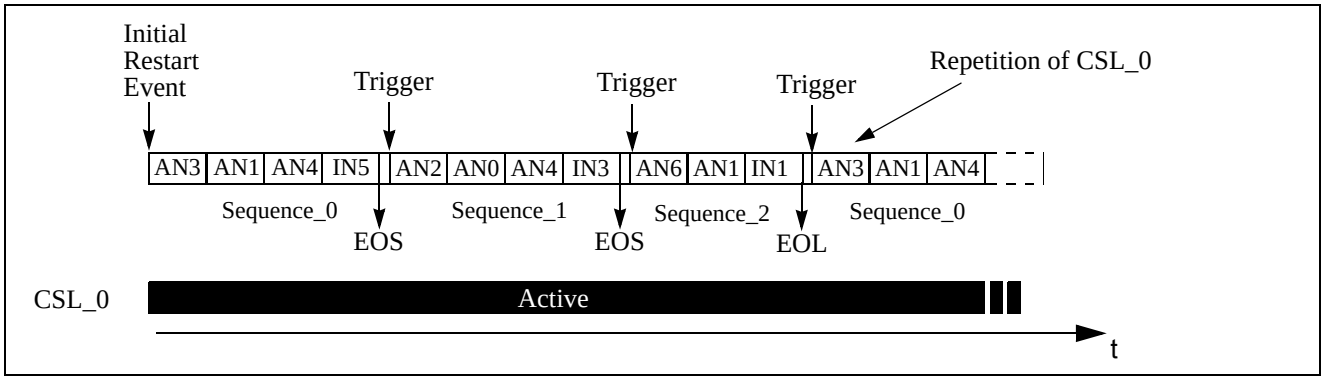

Figure 10-42. Conversion Flow Control Diagram — Triggered Conversion (CSL Repetition)

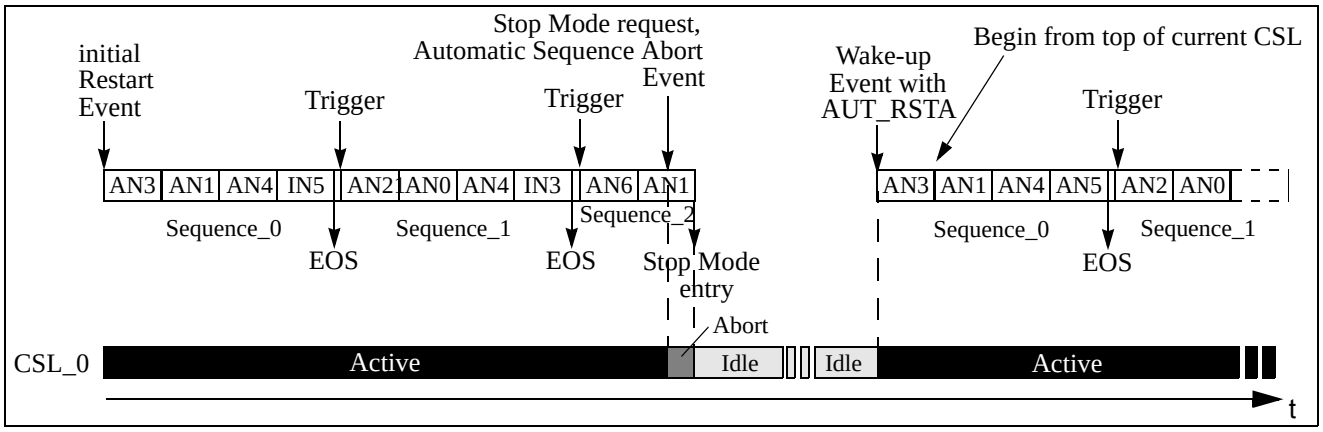

Figure 10-43. Conversion Flow Control Diagram — Triggered Conversion (with Stop Mode)

In case a Low Power Mode is used:
If bit AUT_RSTA is set before Low Power Mode is entered, the conversion continues automatically as soon as a low power mode (Stop Mode or Wait Mode with bit SWAI set) is exited.

Chapter 11
Digital Analog Converter (DAC_8B5V_V2)

11.1 Revision History

Table 11-1. Revision History Table

1.4	17-Nov.-10	11.2.2	Update the behavior of the DACU pin during stop mode
1.5	29-Aug.-13	11.2.2, 11.3	added note about settling time added link to DACM register inside section 11.3
2.0	30-Jan.-14	11.2.3, 11.4.2.1, 11.5.4	added mode “Internal DAC only“
2.1	13-May.-15	Figure 11-5	correct read value of reserved register, Figure 11-5

Glossary

Table 11-2. Terminology

Term	Meaning
DAC	Digital to Analog Converter
VRL	Low Reference Voltage
VRH	High Reference Voltage
FVR	Full Voltage Range
SSC	Special Single Chip

11.2 Introduction

The DAC_8B5V module is a digital to analog converter. The converter works with a resolution of 8 bit and generates an output voltage between VRL and VRH.

The module consists of configuration registers and two analog functional units, a DAC resistor network and an operational amplifier.

The configuration registers provide all required control bits for the DAC resistor network and for the operational amplifier.

The DAC resistor network generates the desired analog output voltage. The unbuffered voltage from the DAC resistor network output can be routed to the external DACU pin. When enabled, the buffered voltage from the operational amplifier output is available on the external AMP pin.

The operational amplifier is also stand alone usable.

Figure 11-1 shows the block diagram of the DAC_8B5V module.

Table 12-6. Amplifier Gain

PGAGAIN[3:0]	Gain A_{PGA}
0000	10x
0001	20x
0010	40x
0011	80x
others	Reserved

12.3.2.4 PGA Offset Register (PGAOFFSET)

Module Base + 0x0003 — Access: User read/write[1]

	7	6	5	4	3	2	1	0
R	0		PGAOFFSET[5:0]					
W								
Reset	0	0	0	0	0	0	0	0

Figure 12-6. PGA Offset Register (PGAOFFSET

[1] Read: Anytime
Write: Anytime

Table 12-7. PGAOFFSET Field Description

Field	Description
5:0 PGAOFFSET [5:0]	**PGA Offset** — These register bits select the offset correction for the PGA, see Table 12-8., "Offset Compensation and 12.4.2, "Offset Compensation.

Table 12-8. Offset Compensation

PGAOFFSET[5:3]	ΔV_{OUT}
0x011	- 3*V_{step_H}
0x010	- 2*V_{step_H}
0x001	- 1*V_{step_H}
0x000	0
0x111	+ 1*V_{step_H}
0x110	+ 2*V_{step_H}
0x101	+ 3*V_{step_H}
0x100	0

PGAOFFSET[2:0]	ΔV_{OUT}
0x011	- 3*V_{step_L}
0x010	- 2*V_{step_L}
0x001	- 1*V_{step_L}
0x000	0
0x111	+ 1*V_{step_L}
0x110	+ 2*V_{step_L}
0x101	+ 3*V_{step_L}
0x100	0

14.3.2.1 BATS Module Enable Register (BATE)

Module Base + 0x0000 Access: User read/write[1]

	7	6	5	4	3	2	1	0
R	0	BVHS	BVLS[1:0]		BSUAE	BSUSE	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented

Figure 14-3. BATS Module Enable Register (BATE)

[1] Read: Anytime
Write: Anytime

Table 14-2. BATE Field Description

Field	Description
6 BVHS	**BATS Voltage High Select** — This bit selects the trigger level for the Voltage Level High Condition (BVHC). 0 Voltage level V_{HBI1} is selected 1 Voltage level V_{HBI2} is selected
5:4 BVLS[1:0]	**BATS Voltage Low Select** — This bit selects the trigger level for the Voltage Level Low Condition (BVLC). 00 Voltage level V_{LBI1} is selected 01 Voltage level V_{LBI2} is selected 10 Voltage level V_{LBI3} is selected 11 Voltage level V_{LBI4} is selected
3 BSUAE	**BATS VSUP ADC Connection Enable** — This bit connects the VSUP pin through the resistor chain to ground and connects the ADC channel to the divided down voltage. 0 ADC Channel is disconnected 1 ADC Channel is connected
2 BSUSE	**BATSV3 VSUP Level Sense Enable** — This bit connects the VSUP pin through the resistor chain to ground and enables the Voltage Level Sense features measuring BVLC and BVHC. 0 Level Sense features disabled 1 Level Sense features enabled

NOTE

When opening the resistors path to ground by changing BSUSE or BSUAE then for a time T_{EN_UNC} + two bus cycles the measured value is invalid. This is to let internal nodes be charged to correct value. BVHIE, BVLIE might be cleared for this time period to avoid false interrupts.

Table 15-7. Compare Result Output Action

OMx	OLx	Action
0	0	No output compare action on the timer output signal
0	1	Toggle OCx output line
1	0	Clear OCx output line to zero
1	1	Set OCx output line to one

15.3.2.7 Timer Control Register 3/Timer Control Register 4 (TCTL3 and TCTL4)

Module Base + 0x000A

	7	6	5	4	3	2	1	0
R W	RESERVED	RESERVED	RESERVED	RESERVED	EDG5B	EDG5A	EDG4B	EDG4A
Reset	0	0	0	0	0	0	0	0

Figure 15-12. Timer Control Register 3 (TCTL3)

Module Base + 0x000B

	7	6	5	4	3	2	1	0
R W	EDG3B	EDG3A	EDG2B	EDG2A	EDG1B	EDG1A	EDG0B	EDG0A
Reset	0	0	0	0	0	0	0	0

Figure 15-13. Timer Control Register 4 (TCTL4)

Read: Anytime

Write: Anytime.

Table 15-8. TCTL3/TCTL4 Field Descriptions

Note: Writing to unavailable bits has no effect. Reading from unavailable bits return a zero.

Field	Description
5:0 EDGnB EDGnA	**Input Capture Edge Control** — These six pairs of control bits configure the input capture edge detector circuits.

Table 15-9. Edge Detector Circuit Configuration

EDGnB	EDGnA	Configuration
0	0	Capture disabled
0	1	Capture on rising edges only
1	0	Capture on falling edges only
1	1	Capture on any edge (rising or falling)

Table 18-11. SCISR1 Field Descriptions (continued)

Field	Description
1 FE	**Framing Error Flag** — FE is set when a logic 0 is accepted as the stop bit. FE bit is set during the same cycle as the RDRF flag but does not get set in the case of an overrun. FE inhibits further data reception until it is cleared. Clear FE by reading SCI status register 1 (SCISR1) with FE set and then reading the SCI data register low (SCIDRL). 0 No framing error 1 Framing error
0 PF	**Parity Error Flag** — PF is set when the parity enable bit (PE) is set and the parity of the received data does not match the parity type bit (PT). PF bit is set during the same cycle as the RDRF flag but does not get set in the case of an overrun. Clear PF by reading SCI status register 1 (SCISR1), and then reading SCI data register low (SCIDRL). 0 No parity error 1 Parity error

18.3.2.8 SCI Status Register 2 (SCISR2)

Module Base + 0x0005

	7	6	5	4	3	2	1	0
R	AMAP	0	0	TXPOL	RXPOL	BRK13	TXDIR	RAF
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 18-11. SCI Status Register 2 (SCISR2)

Read: Anytime

Write: Anytime

Table 18-12. SCISR2 Field Descriptions

Field	Description
7 AMAP	**Alternative Map** — This bit controls which registers sharing the same address space are accessible. In the reset condition the SCI behaves as previous versions. Setting AMAP=1 allows the access to another set of control and status registers and hides the baud rate and SCI control Register 1. 0 The registers labelled SCIBDH (0x0000),SCIBDL (0x0001), SCICR1 (0x0002) are accessible 1 The registers labelled SCIASR1 (0x0000),SCIACR1 (0x0001), SCIACR2 (0x00002) are accessible
4 TXPOL	**Transmit Polarity** — This bit control the polarity of the transmitted data. In NRZ format, a one is represented by a mark and a zero is represented by a space for normal polarity, and the opposite for inverted polarity. In IrDA format, a zero is represented by short high pulse in the middle of a bit time remaining idle low for a one for normal polarity, and a zero is represented by short low pulse in the middle of a bit time remaining idle high for a one for inverted polarity. 0 Normal polarity 1 Inverted polarity

Figure 18-17 shows two cases of break detect. In trace RXD_1 the break symbol starts with the start bit, while in RXD_2 the break starts in the middle of a transmission. If BRKDFE = 1, in RXD_1 case there will be no byte transferred to the receive buffer and the RDRF flag will not be modified. Also no framing error or parity error will be flagged from this transfer. In RXD_2 case, however the break signal starts later during the transmission. At the expected stop bit position the byte received so far will be transferred to the receive buffer, the receive data register full flag will be set, a framing error and if enabled and appropriate a parity error will be set. Once the break is detected the BRKDIF flag will be set.

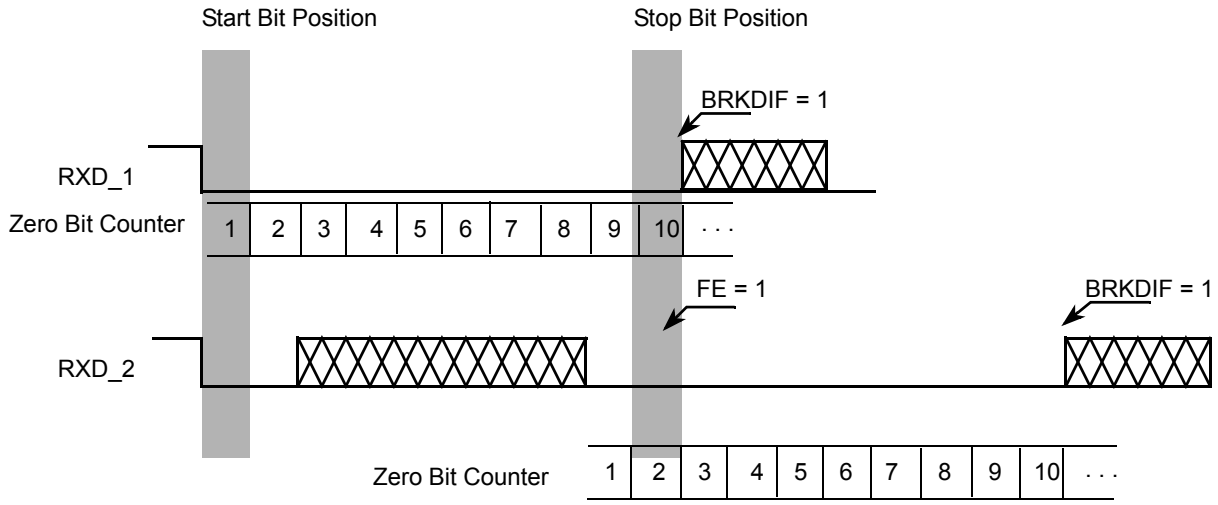

Figure 18-17. Break Detection if BRKDFE = 1 (M = 0)

18.4.5.4 Idle Characters

An idle character (or preamble) contains all logic 1s and has no start, stop, or parity bit. Idle character length depends on the M bit in SCI control register 1 (SCICR1). The preamble is a synchronizing idle character that begins the first transmission initiated after writing the TE bit from 0 to 1.

If the TE bit is cleared during a transmission, the TXD pin becomes idle after completion of the transmission in progress. Clearing and then setting the TE bit during a transmission queues an idle character to be sent after the frame currently being transmitted.

NOTE

When queueing an idle character, return the TE bit to logic 1 before the stop bit of the current frame shifts out through the TXD pin. Setting TE after the stop bit appears on TXD causes data previously written to the SCI data register to be lost. Toggle the TE bit for a queued idle character while the TDRE flag is set and immediately before writing the next byte to the SCI data register.

If the TE bit is clear and the transmission is complete, the SCI is not the master of the TXD pin

NOTE

When peripherals with duplex capability are used, take care not to simultaneously enable two receivers whose serial outputs drive the same system slave's serial data output line.

As long as no more than one slave device drives the system slave's serial data output line, it is possible for several slaves to receive the same transmission from a master, although the master would not receive return information from all of the receiving slaves.

If the CPHA bit in SPI control register 1 is clear, odd numbered edges on the SCK input cause the data at the serial data input pin to be latched. Even numbered edges cause the value previously latched from the serial data input pin to shift into the LSB or MSB of the SPI shift register, depending on the LSBFE bit.

If the CPHA bit is set, even numbered edges on the SCK input cause the data at the serial data input pin to be latched. Odd numbered edges cause the value previously latched from the serial data input pin to shift into the LSB or MSB of the SPI shift register, depending on the LSBFE bit.

When CPHA is set, the first edge is used to get the first data bit onto the serial data output pin. When CPHA is clear and the $\overline{SS}$ input is low (slave selected), the first bit of the SPI data is driven out of the serial data output pin. After the nth[1] shift, the transfer is considered complete and the received data is transferred into the SPI data register. To indicate transfer is complete, the SPIF flag in the SPI status register is set.

NOTE

A change of the bits CPOL, CPHA, SSOE, LSBFE, MODFEN, SPC0, or BIDIROE with SPC0 set in slave mode will corrupt a transmission in progress and must be avoided.

19.4.3 Transmission Formats

During an SPI transmission, data is transmitted (shifted out serially) and received (shifted in serially) simultaneously. The serial clock (SCK) synchronizes shifting and sampling of the information on the two serial data lines. A slave select line allows selection of an individual slave SPI device; slave devices that are not selected do not interfere with SPI bus activities. Optionally, on a master SPI device, the slave select line can be used to indicate multiple-master bus contention.

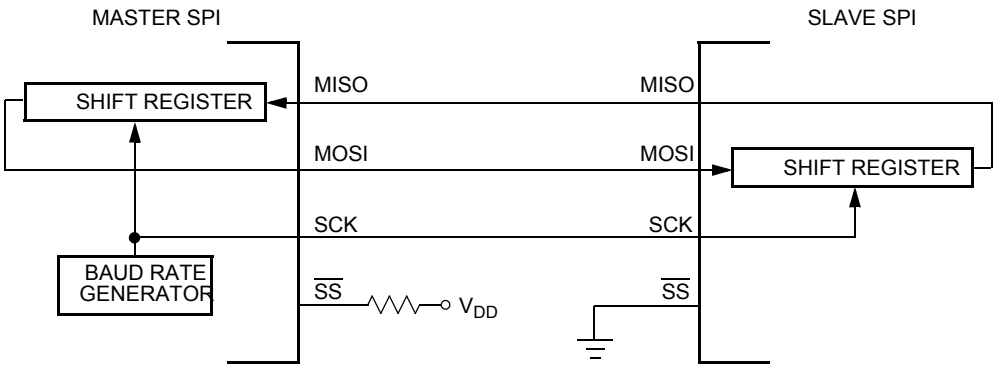

Figure 19-11. Master/Slave Transfer Block Diagram

1. n depends on the selected transfer width, please refer to Section 19.3.2.2, "SPI Control Register 2 (SPICR2)

21.4 Functional Description

21.4.1 General

The S12LINPHYV2 module implements the physical layer of the LIN interface. This physical layer can be driven by the SCI (Serial Communication Interface) module or directly through the LPDR register.

21.4.2 Slew Rate and LIN Mode Selection

The slew rate can be selected for Electromagnetic Compatibility (EMC) optimized operation at 10.4 kbit/s and 20 kbit/s as well as at fast baud rate (up to 250 kbit/s) for test and programming. The slew rate can be chosen with the bits LPSLR[1:0] in the LIN Slew Rate Mode Register (LPSLRM). The default slew rate corresponds to 20 kbit/s.

The LIN Physical Layer can also be configured to be used for non-LIN applications (for example, to transmit a PWM pulse) by disabling the TxD-dominant timeout (LPDTDIS=1).

Changing the slew rate (LPSLRM Register) during transmission is not allowed in order to avoid unwanted effects. To change the register, the LIN Physical Layer must first be disabled (LPE=0). Once it is updated the LIN Physical Layer can be enabled again.

NOTE

For 20 kbit/s and Fast Mode communication speeds, the corresponding slew rate ***MUST*** be set; otherwise, the communication is not guaranteed (violation of the specified LIN duty cycles). For 10.4 kbit/s, the 20 kbit/s slew rate ***can*** be set but the EMC performance is worse. The up to 250 kbit/s slew rate must be chosen ***ONLY*** for fast mode, not for any of the 10.4 kbit/s or 20 kbit/s LIN compliant communication speeds.

21.4.2.1 10.4 kbit/s and 20 kbit/s

When the slew rate is chosen for 10.4 kbit/s or 20 kbit/s communication, a control loop is activated within the module to make the rise and fall times of the LIN bus independent from VLINSUP and the load on the bus.

21.4.2.2 Fast Mode (not LIN compliant)

Choosing this slew rate allows baud rates up to 250 kbit/s by having much steeper edges (please refer to electricals). As for the 10.4 kbit/s and 20 kbit/s modes, the slope control loop is also engaged. This mode is used for fast communication only, and the LIN electricals are not supported (for example, the LIN duty cycles).

A stronger external pullup resistor might be necessary to sustain communication speeds up to 250 kbit/s. The LIN signal (and therefore the receive LPRxD signal) might not be symmetrical for high baud rates with high loads on the bus.

Table 22-18. FPROT Field Descriptions (continued)

Field	Description
2 FPLDIS	**Flash Protection Lower Address Range Disable** — The FPLDIS bit determines whether there is a protected/unprotected area in a specific region of the P-Flash memory beginning with global address 0xFF_8000. 0 Protection/Unprotection enabled 1 Protection/Unprotection disabled
1–0 FPLS[1:0]	**Flash Protection Lower Address Size** — The FPLS bits determine the size of the protected/unprotected area in P-Flash memory as shown in Table 22-21. The FPLS bits can only be written to while the FPLDIS bit is set.

Table 22-19. P-Flash Protection Function

FPOPEN	FPHDIS	FPLDIS	Function[1]
1	1	1	No P-Flash Protection
1	1	0	Protected Low Range
1	0	1	Protected High Range
1	0	0	Protected High and Low Ranges
0	1	1	Full P-Flash Memory Protected
0	1	0	Unprotected Low Range
0	0	1	Unprotected High Range
0	0	0	Unprotected High and Low Ranges

1 For range sizes, refer to Table 22-20 and Table 22-21.

Table 22-20. P-Flash Protection Higher Address Range

FPHS[1:0]	Global Address Range	Protected Size
00	0xFF_F800–0xFF_FFFF	2 KB
01	0xFF_F000–0xFF_FFFF	4 KB
10	0xFF_E000–0xFF_FFFF	8 KB
11	0xFF_C000–0xFF_FFFF	16 KB

Table 22-21. P-Flash Protection Lower Address Range

FPLS[1:0]	Global Address Range	Protected Size
00	0xFF_8000–0xFF_83FF	1 KB
01	0xFF_8000–0xFF_87FF	2 KB
10	0xFF_8000–0xFF_8FFF	4 KB
11	0xFF_8000–0xFF_9FFF	8 KB

All possible P-Flash protection scenarios are shown in Figure 22-14 . Although the protection scheme is loaded from the Flash memory at global address 0xFF_FE0C during the reset sequence, it can be changed by the user. The P-Flash protection scheme can be used by applications requiring reprogramming in normal single chip mode while providing as much protection as possible if reprogramming is not required.

22.4.7.10 Unsecure Flash Command

The Unsecure Flash command will erase the entire P-Flash and EEPROM memory space and, if the erase is successful, will release security.

Table 22-51. Unsecure Flash Command FCCOB Requirements

Register	FCCOB Parameters	
FCCOB0	0x0B	Not required

Upon clearing CCIF to launch the Unsecure Flash command, the Memory Controller will erase the entire P-Flash and EEPROM memory space and verify that it is erased. If the Memory Controller verifies that the entire Flash memory space was properly erased, security will be released. If the erase verify is not successful, the Unsecure Flash operation sets MGSTAT1 and terminates without changing the security state. During the execution of this command (CCIF=0) the user must not write to any Flash module register. The CCIF flag is set after the Unsecure Flash operation has completed.

Table 22-52. Unsecure Flash Command Error Handling

Register	Error Bit	Error Condition
FSTAT	ACCERR	Set if CCOBIX[2:0] != 000 at command launch
		Set if command not available in current mode (see Table 22-28)
	FPVIOL	Set if any area of the P-Flash or EEPROM memory is protected
	MGSTAT1	Set if any errors have been encountered during the verify operation
	MGSTAT0	Set if any non-correctable errors have been encountered during the verify operation

22.4.7.11 Verify Backdoor Access Key Command

The Verify Backdoor Access Key command will only execute if it is enabled by the KEYEN bits in the FSEC register (see Table 22-9). The Verify Backdoor Access Key command releases security if user-supplied keys match those stored in the Flash security bytes of the Flash configuration field (see Table 22-3). The Verify Backdoor Access Key command must not be executed from the Flash block containing the backdoor comparison key to avoid code runaway.

Table 22-53. Verify Backdoor Access Key Command FCCOB Requirements

Register	FCCOB Parameters	
FCCOB0	0x0C	Not required
FCCOB1	Key 0	
FCCOB2	Key 1	
FCCOB3	Key 2	
FCCOB4	Key 3	